



Features	XPort®	XPort® Pro	XPort® Pro Lx6	xPico®	xPico Wi-Fi®	PremierWave® EN	PremierWave® SE1000	PremierWave® 2050
<b>Category</b>	Wired Device Server				Wireless Device Server	System on Module		Enterprise Wi-Fi Bridge
<b>Mounting Option</b>					Connector/SMT‡	Connector	Connector	SMT
<b>Operating System</b>	CoBos	Evolution OS®/Linux	Evolution OS®/Linux	CoBos	ThreadX	Linux	Linux	Linux
<b>10/100 Ethernet</b> (*External RJ45 Jack)	•	•	•	•*		•*	•*	•
<b>Wireless 802.11</b>					b/g/n	a/b/g/n		a/b/g/n/ac
<b>Antenna Options</b>					On Module or External‡	On Module or External‡		On Module or External‡
<b>LAN &gt; 802.11 Bridging</b>						•		•
<b>Simultaneous Soft AP and Client</b>					•			•
<b>Enterprise Wi-Fi Security</b>						•		•
<b>SmartRoam™</b>						•		
<b>TCP / UDP Client-Server</b>	•	•	•	•	•(tUDP)	•	•	
<b>Telnet</b>	•	•	•	•		•		•
<b>DHCP, BOOTP &amp; AUTOIP</b>	•	•	•	•	•	•	•	•
<b>TFTP</b>	•	•	•	•				
<b>FTP</b>		•	•			•	•	•
<b>PPP</b>		•	•			•	•	
<b>SNMP v1/v2</b>	•	•	•	•		•	•	•
<b>Modbus</b> (*Available in IAP)	•*			•*				
<b>Web Server - HTTP/CGI</b> (*Custom)	•*	•*	•*	•*	•	•*	•*	•
<b>Web Server - AJAX</b>		•	•			•*	•	•
<b>SSL Secure Web Server</b>		•				•	•	•
<b>SSL Secure Data Tunneling</b>		•				•	•	•
<b>SSH Client &amp; Server</b>		•				•	•	•
<b>IPv6</b> (*Linux SDK Development Platform)			•		•†	•*	•*	•
<b>AES Encryption</b>	• ‡	•	•	• ‡	•	•	•	•
<b>Max Configurable GPIO Pins</b> (*RTS/CTS on Configurable Pins)	3*	3*	3*	8	8	9	9	13
<b>Software Development Kit</b> (Alpha)	• ‡	•	•	• ‡		•	•	•*
<b>Flash/RAM</b>	512KB/256KB	16MB/16MB	16MB/16MB	512KB/256KB	1MB/128KB	64MB/64MB	64MB/64MB 256MB/64MB	128MB/64MB
<b>Maximum Serial Data Rate</b>	921 Kbps	921 Kbps	921 Kbps	921 Kbps	921 Kbps	921 Kbps	921 Kbps	921 Kbps
<b>Web Manager</b> (for Configuration)	•	•	•	•	•	•	•	•
<b>Email Client</b> (*Subject Line Only)	•*	•	•	•*		•	•	
<b>Operating Temperature</b> (C°/F°)	-40 to 85°C / -40 to 185°F	-40 to 85°C / -40 to 185°F	-40 to 85°C / -40 to 185°F	-40 to 85°C / -40 to 185°F	-40 to 85°C / -40 to 185°F	-40 to 85°C / -40 to 185°F	-40 to 85°C / -40 to 185°F	-40 to 85°C / -40 to 185°F
<b>Dimensions</b> (mm; +/-0.3mm)	33.9 x 16.25 x 13.5	33.9 x 16.25 x 13.5	33.9 x 16.25 x 13.5	24 x 16.5 x 5.64	SMT (1002): 301 x 18.3 x 3.0 SMT (1003): 261 x 18.3 x 3.0 24 x 16.5 x 5.64	30 x 55 x 8	30 x 55 x 8	46.66 x 45.07 x 3.5
<b>Serial Interface/# of Ports</b> (*5V Tolerance)	CMOS 3.3V*/1	CMOS 3.3V*/1	CMOS 3.3V*/1	CMOS 3.3V*/2	CMOS 3.3V*/2	CMOS 3.3V*/2	CMOS 3.3V*/2	CMOS 3.3V*/2
<b>SPI Interface</b>					•†	•	•	•
<b>USB</b> (*Full Speed Only)					•*†	Device & Host	Device & Host	Device & Host

† Available in future software release ‡ Version dependent

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